S99.840SD7215 June 26, 2003 Express Mail No. EV332389041US

IN THE U.S. PATENT AND TRADEMARK OFFICE

APPLICANTS:

James M. Gee and Russell Schmit

SERIAL NO.:

Unknown

GROUP NO.

FILED:

EXAMINER:

FOR:

Fabrication of Back-Contacted Silicon Solar Cells Using Thermomigration to

Create Conductive Vias

Assistant Commissioner for Patents Washington, D.C. 20231

June 26, 2003

INFORMATION DISCLOSURE STATEMENT

The following sections are being submitted for this Information Disclosure Statement:

1. Preliminary Statements

Applicants submit herewith patents, publications or other information of which they are: aware, which they believe may be material to the examination of this application and in respect of which there may be a duty to disclose.

The filing of this Information Disclosure Statement shall not be construed as a representation that a search has been made (37 CFR 1.97(g)), an admission that the information cited is, or is considered to be, material to patentability or that no other material information exists.

The filing of this Information Disclosure Statement shall not be construed as an admission against interest in any manner. Notice of January 9, 1992, 1135 O.G. 13-25, at 25.

- 2. Form PTO 1449 (Modified).
- 3. The person making this statement is the attorney or agent who signs below on the basis of the information supplied by the inventor(s) and the information in the attorney's or agent's file.

Dated:

6/28/03

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CERTIFICATE OF MAILING

I hereby certify that this paper (along with any referred to as being attached or enclosed) is being deposited with the U. S. Postal Service on the date shown below as Express Mail No. V332389041US in an envelope addressed to the: Assistant Commissioner for Patents, Box Patent Application, Washington, D.C. 20231.

Dated: 6/26/03

Tola Campos

Form PTO-1449 (SNL-Modified) (2-91)

List of Patents and Publications

for Applicant's

Information Disclosure Statement

(use several sheets if necessary)

Atty Docket No: SD-7215/S-99,840

Serial Number:

APPLICANT: Jamés M. Gee & Russell R.

Schmit

GROUP: FILING DATE: 6/26/03

REFERENCE DESIGNATION

Ex'r			U.S	S. Patent Documents	Sub		
Init	_	Document l	No. Date	Name Cl	ass Class	File Date	
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	AB	4,173,496	11/6/79	Inregrated Solar Cell Arra	y 136/89	5/30/78	
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	AE	4,377,423	3/22/83	Liquid Metal Inclusion	148/171	4/28/82	
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Examiner:	Date Considered: